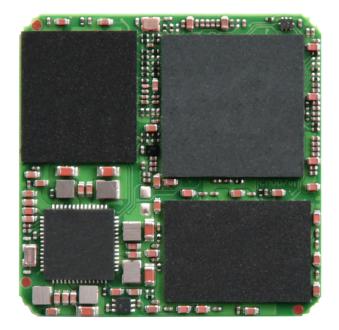
## Embedded Module with i.MX8M Nano

Open Standard Module<sup>™</sup> - iesy i.MX8M Nano OSM-SF

## **Technical Concept**

►	Processor:	i.MX8M Mini Cortex-A53 Solo Core
►	CPU Clock-Rate:	1.5 GHz
►	RAM:	512 MByte LPDDR4
►	Flash-Memory:	8 GByte e-MMC 5.1
►	Dimension:	30 mm x 30 mm
Þ	Footprint:	OSM Size-S Land Grid Array (LGA) with 332 contacts
►	Supply:	Single Supply 5VDC
•	Temperature range: > Operating: > Storage:	-40 °C to +85 °C / 0 °C bis +85 °C -40 °C to +85 °C

- Power consumption: < 5W (typ.)</p>
- ► Features & Interfaces
  - > 1 × LAN 10/100/1000 (RGMII)
  - > 1x PCle x1
  - > 1x USB 2.0 Host
  - > 1x USB 2.0 OTG
  - > 1x MIPI DSI (4 Lanes)
  - > 1x MIPI CSI (4 Lanes)
  - > 1x SD-Card, 1x SDIO/MMC (x8)
  - > 1x QSPI, 1x SPI, 4x UART
  - > 2x I2C, 1x I2S (2x TX/RX)
  - > 24x GPIO, 3x PWM
  - > 1x JTAG



## About OSM<sup>™</sup>

The Open Standard Modules<sup>™</sup> specification was adopted by the SGeT e.V. in 2019. The new standard was developed to meet future requirements in terms of **flexibility**, **scalability**, but also **costs**. OSM<sup>™</sup> solder-down modules can be **individually adapted** to the respective customer requirements. For this purpose, the individual modules can be made **available to the SMT process** by means of tray & reel packaging and processed automatically. The OSM<sup>™</sup> series includes in total four different form factors.

